

- Members of the Texas Instruments *Widebus™* Family
- Inputs Are TTL-Voltage Compatible
- 3-State Outputs Drive Bus Lines Directly
- Flow-Through Architecture Optimizes PCB Layout
- Distributed V_{CC} and GND Configuration to Minimize High-Speed Switching Noise
- *EPIC™* (Enhanced-Performance Implanted CMOS) 1- μ m Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Packages Using 25-mil Center-to-Center Pin Spacings, Thin Shrink Small-Outline (DGG) Packages, and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Pin Spacings

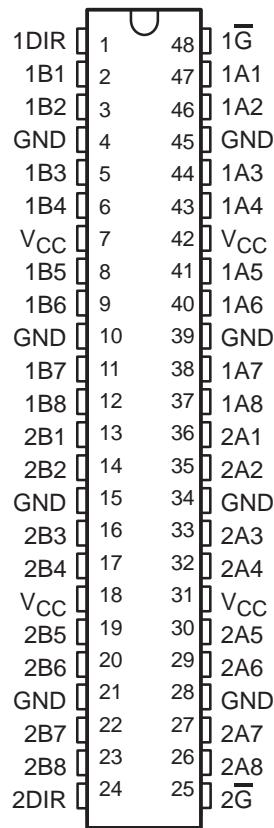
description

The SN54ACT16245 and 74ACT16245 are 16-bit bus transceivers organized as dual-octal noninverting 3-state transceivers and designed for asynchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

The devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The enable (\bar{G}) input can be used to disable the devices so that the buses are effectively isolated.

The SN54ACT16245 is characterized for operation over the full military temperature range of -55°C to 125°C . The 74ACT16245 is characterized for operation from -40°C to 85°C .

SN54ACT16245 . . . WD PACKAGE
74ACT16245 . . . DGG OR DL PACKAGE
(TOP VIEW)



FUNCTION TABLE

CONTROL INPUTS		OPERATION
\bar{G}	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation



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 **TEXAS
INSTRUMENTS**

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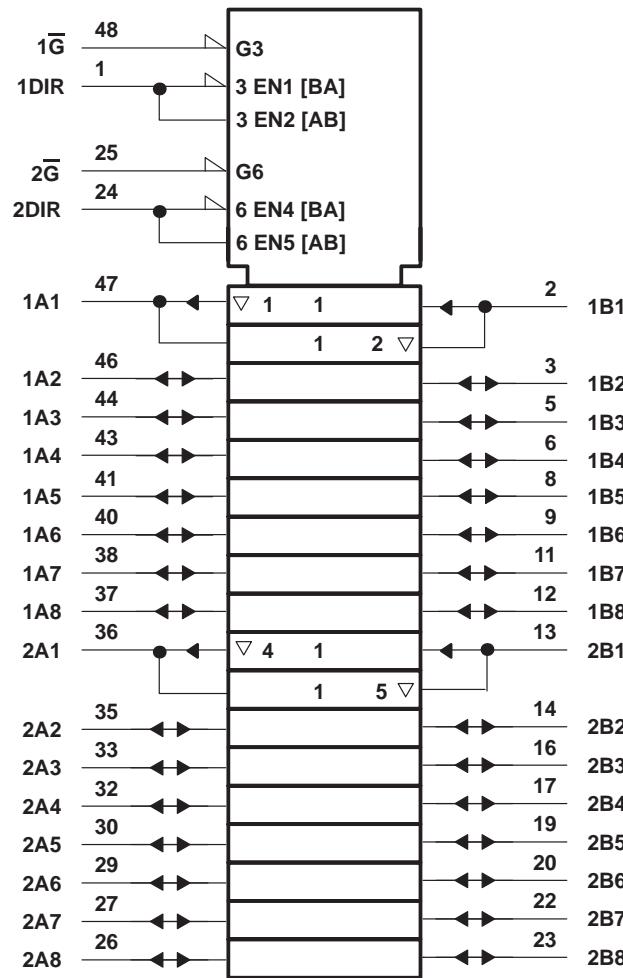
SN54ACT16245, 74ACT16245

16-BIT BUS TRANSCEIVERS

WITH 3-STATE OUTPUTS

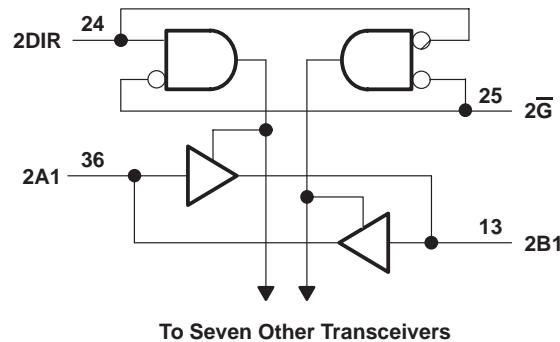
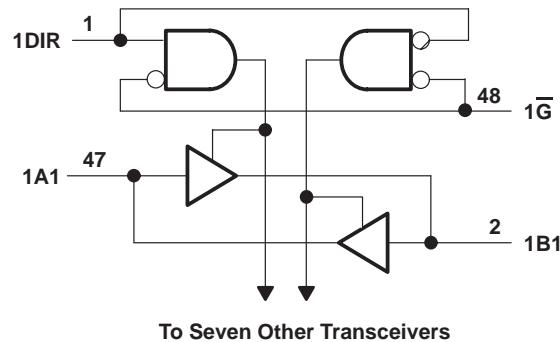
SCAS097B - DECEMBER 1989 - REVISED APRIL 1996

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC}	–0.5 V to 7 V	
Input voltage range, V_I (see Note 1)	–0.5 V to V_{CC} + 0.5 V	
Output voltage range, V_O (see Note 1)	–0.5 V to V_{CC} + 0.5 V	
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA	
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±50 mA	
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA	
Continuous current through V_{CC} or GND	±400 mA	
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 2): DGG package	0.85 W	
DL package	1.2 W	
Storage temperature range, T_{stg}	–65°C to 150°C	

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 3)

		SN54ACT16245		74ACT16245		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage (see Note 4)	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–24	mA
I_{OL}	Low-level output current		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	10	0	10	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTES: 3. Unused inputs should be tied to V_{CC} through a pullup resistor of approximately 5 kΩ or greater to keep them from floating.
4. All V_{CC} and GND pins must be connected to the proper voltage power supply.

SN54ACT16245, 74ACT16245

16-BIT BUS TRANSCEIVERS

WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54ACT16245	74ACT16245	UNIT
			MIN	TYP	MAX	MIN	MAX	
V _{OH}	I _{OH} = -50 µA	4.5 V	4.4			4.4	4.4	V
		5.5 V	5.4			5.4	5.4	
	I _{OH} = -24 mA	4.5 V	3.94			3.94	3.8	
		5.5 V	4.94			4.94	4.8	
	I _{OH} = -50 mA [†]	5.5 V				3.85		
	I _{OH} = -75 mA [†]	5.5 V					3.85	
V _{OL}	I _{OL} = 50 µA	4.5 V		0.1		0.1	0.1	V
		5.5 V		0.1		0.1	0.1	
	I _{OL} = 24 mA	4.5 V		0.36		0.5	0.44	
		5.5 V		0.36		0.5	0.44	
	I _{OL} = 50 mA [†]	5.5 V				1.65		
	I _{OL} = 75 mA [†]	5.5 V					1.65	
I _I	Control inputs	V _I = V _{CC} or GND	5.5 V		±0.1		±1	±1 µA
I _{OZ}	A or B ports [‡]	V _O = V _{CC} or GND	5.5 V		±0.5		±10	±5 µA
I _{CC}		V _I = V _{CC} or GND, I _O = 0	5.5 V		8	160	80	µA
ΔI _{CC} [§]		One input at 3.4 V, Other inputs at GND or V _{CC}	5.5 V		0.9	1	1	mA
C _i	Control inputs	V _I = V _{CC} or GND	5 V		4.5			pF
C _{io}	A or B ports	V _O = V _{CC} or GND	5 V		16			pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

[‡] For I/O ports, the parameter I_{OZ} includes the input leakage current I_I.

[§] This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

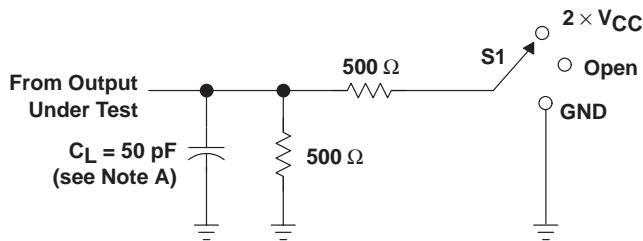
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T _A = 25°C			SN54ACT16245	74ACT16245	UNIT
			MIN	TYP	MAX	MIN	MAX	
t _{PLH}	A or B	B or A	3.2	6.9	9.3	3.2	11.5	3.2 10.5
t _{PHL}			2.6	6.4	9.2	2.6	11.1	2.6 10.2
t _{PZH}	G̅	B or A	2.7	6.4	9.1	2.7	10.9	2.7 10
t _{PZL}			3.4	7.4	10.5	3.4	12.6	3.4 11.6
t _{PHZ}	G̅	B or A	5.8	9.2	11.6	5.8	13.4	5.8 12.6
t _{PLZ}			5.5	8.5	10.8	5.5	12.7	5.5 11.8

operating characteristics, V_{CC} = 5 V, T_A = 25°C

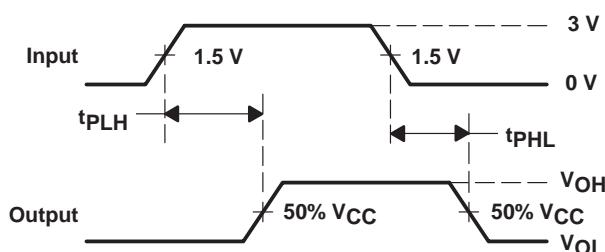
PARAMETER			TEST CONDITIONS		TYP	UNIT
C _{pd}	Power dissipation capacitance per transceiver		Outputs enabled	C _L = 50 pF, f = 1 MHz	52	pF
			Outputs disabled		10	

PARAMETER MEASUREMENT INFORMATION

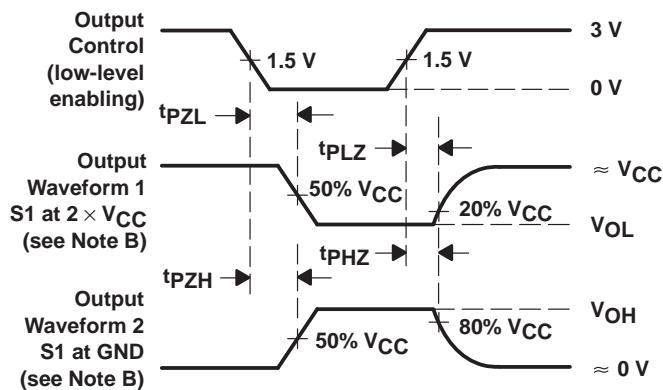


TEST	S1
t _{PLH} /t _{PHL}	Open
t _{PZL} /t _{PZL}	2 \times V _{CC}
t _{PHZ} /t _{PZH}	GND

LOAD CIRCUIT



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

NOTES:

- C_L includes probe and jig capacitance.
- Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_r = 3 \text{ ns}$, $t_f = 3 \text{ ns}$.
- The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
5962-9202301Mxa	Active	Production	CFP (WD) 48	15 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9202301MX A SNJ54ACT16245WD
74ACT16245DGGR	Active	Production	TSSOP (DGG) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16245
74ACT16245DGGR.A	Active	Production	TSSOP (DGG) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16245
74ACT16245DL	Obsolete	Production	SSOP (DL) 48	-	-	Call TI	Call TI	-40 to 85	ACT16245
74ACT16245DLR	Active	Production	SSOP (DL) 48	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16245
74ACT16245DLR.A	Active	Production	SSOP (DL) 48	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16245
74ACT16245DLRG4	Active	Production	SSOP (DL) 48	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16245
SNJ54ACT16245WD	Active	Production	CFP (WD) 48	15 TUBE	No	SNPB	N/A for Pkg Type	-	5962-9202301MX A SNJ54ACT16245WD
SNJ54ACT16245WD.A	Active	Production	CFP (WD) 48	15 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9202301MX A SNJ54ACT16245WD

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

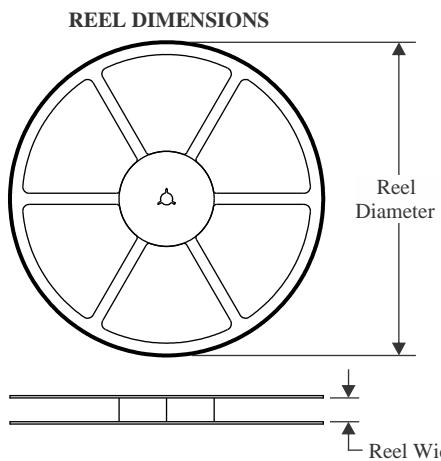
⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

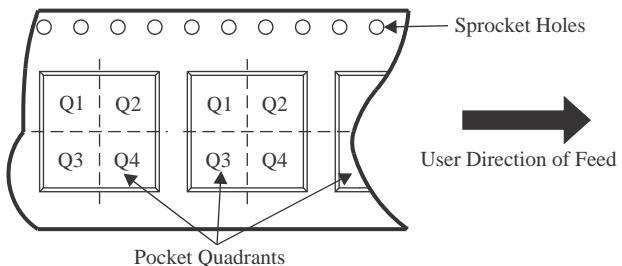
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ACT16245DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
74ACT16245DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

TAPE AND REEL BOX DIMENSIONS

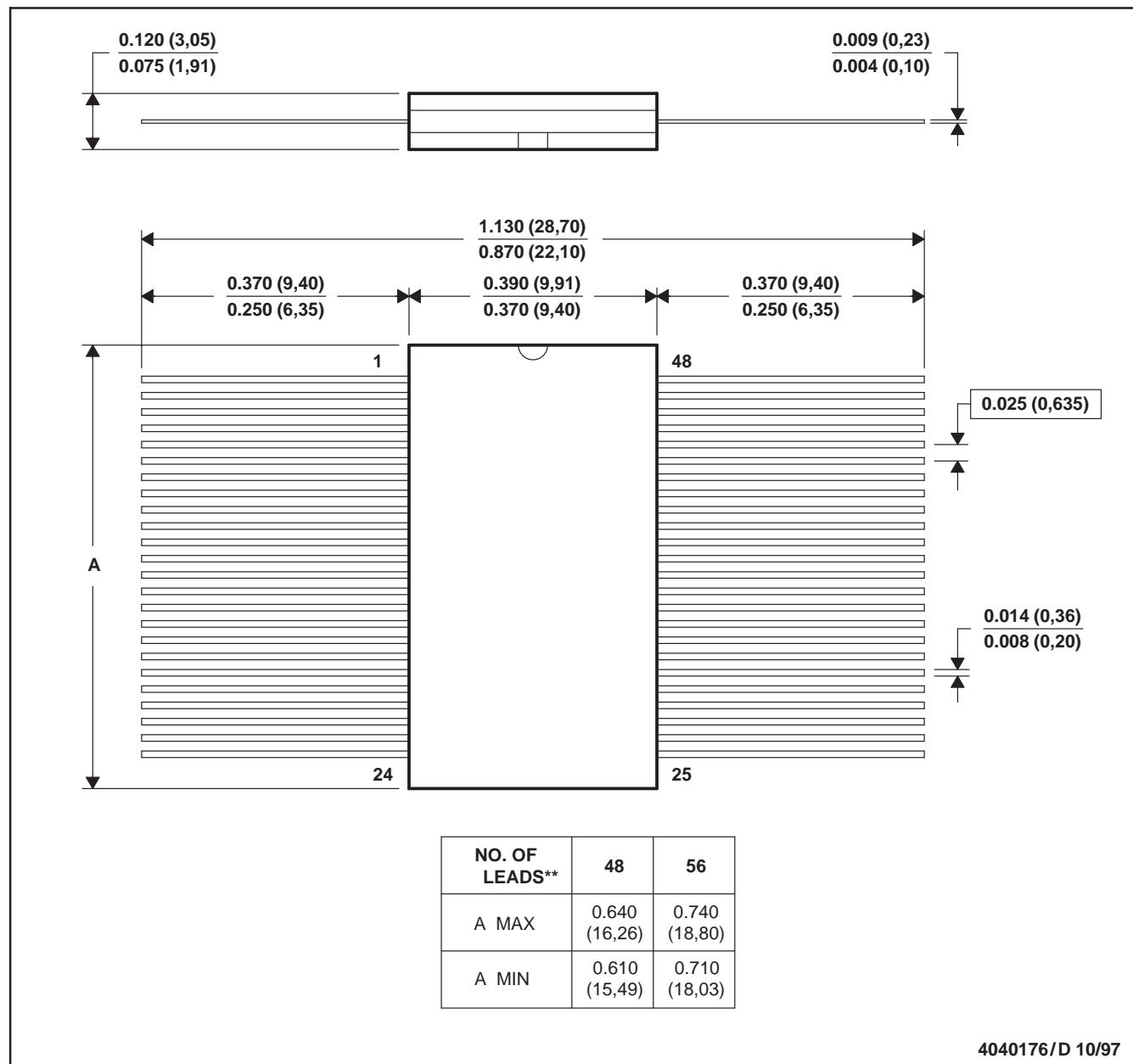

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74ACT16245DGGR	TSSOP	DGG	48	2000	356.0	356.0	45.0
74ACT16245DLR	SSOP	DL	48	1000	356.0	356.0	53.0

WD (R-GDFP-F**)

CERAMIC DUAL FLATPACK

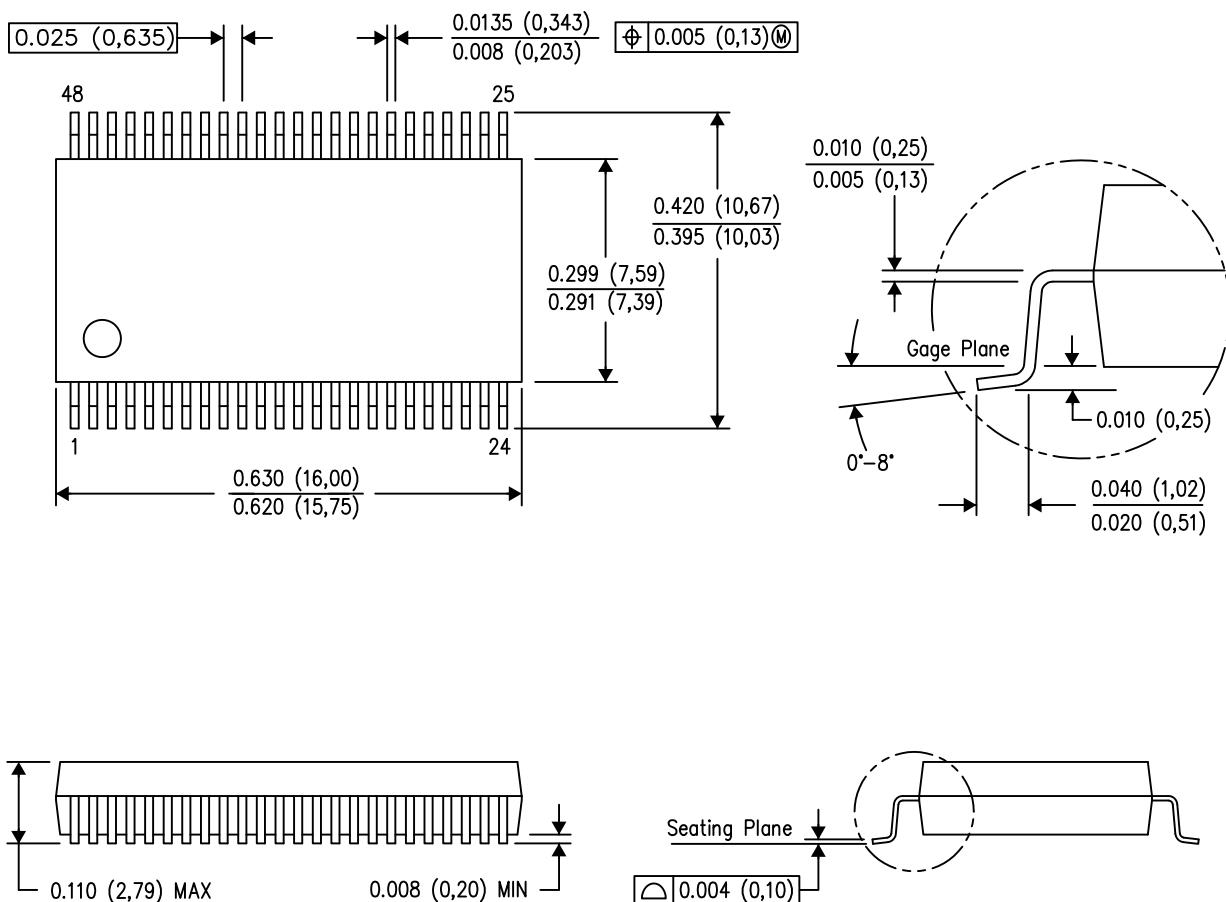
48 LEADS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification only.
 E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA
 GDFP1-F56 and JEDEC MO-146AB

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



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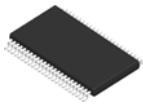
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC M0-118

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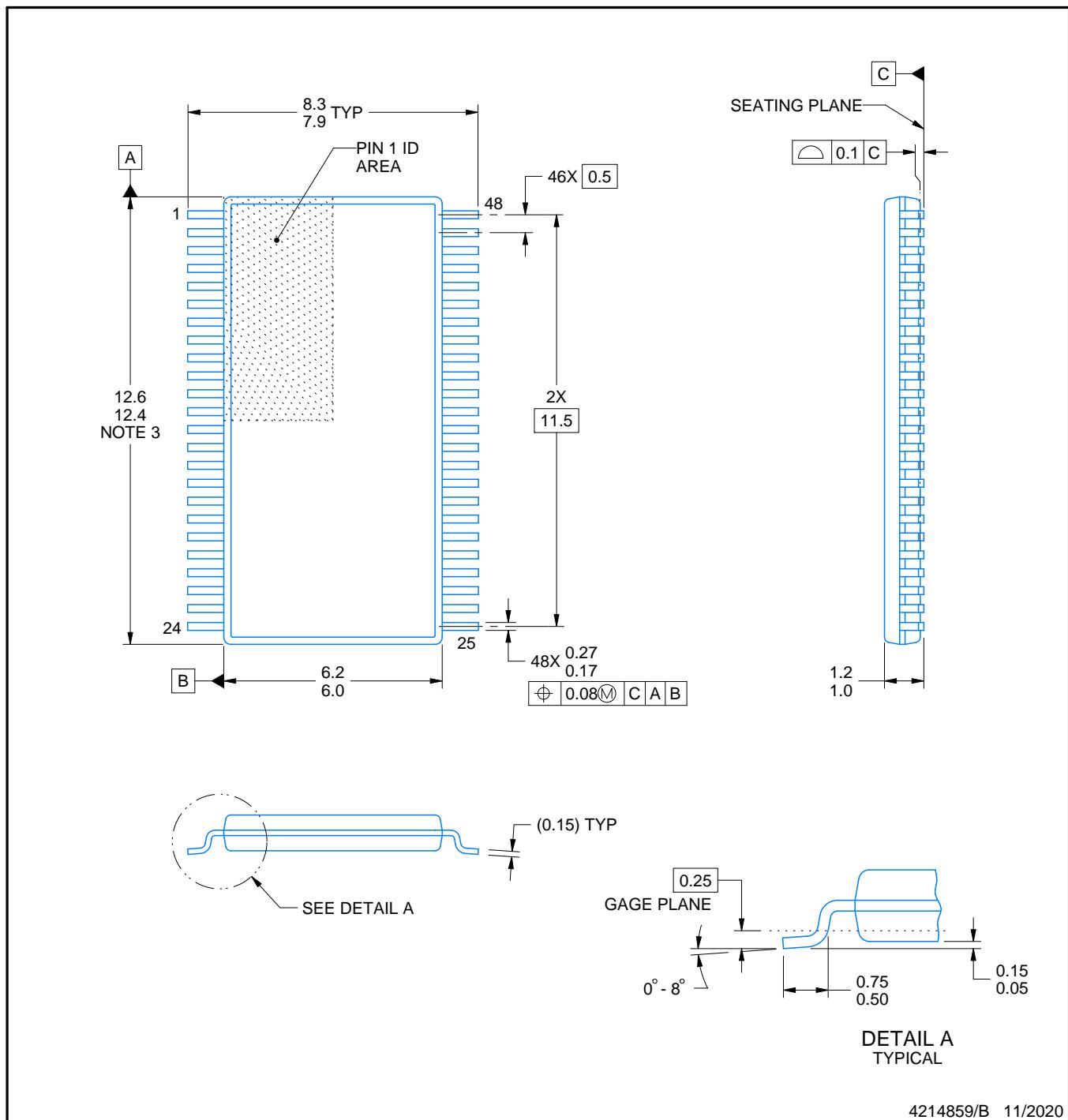
PACKAGE OUTLINE

DGG0048A



TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

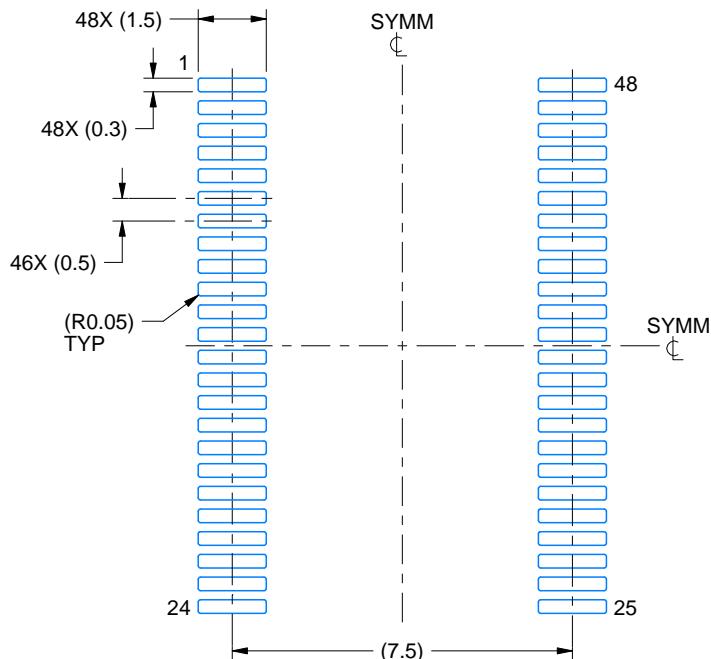
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

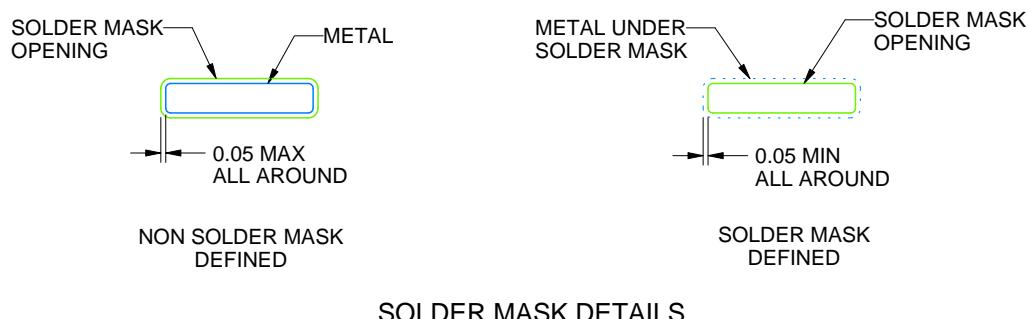
DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4214859/B 11/2020

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

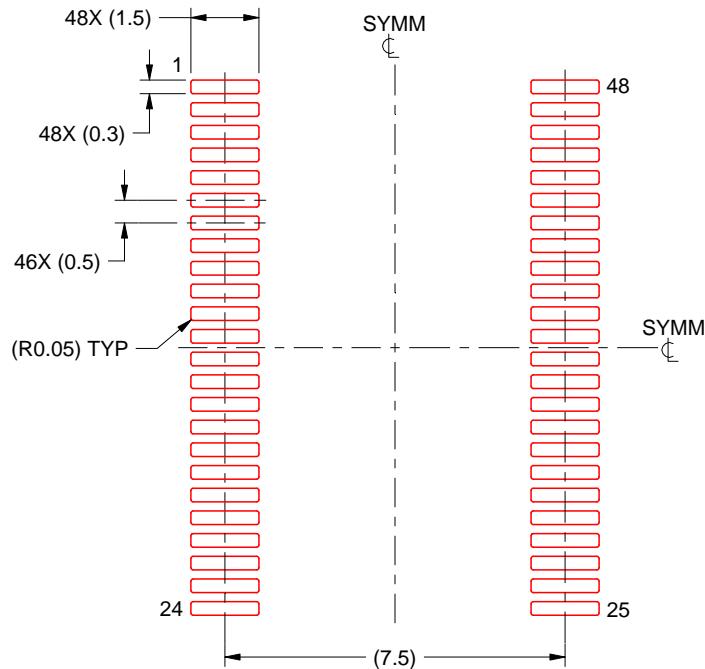
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4214859/B 11/2020

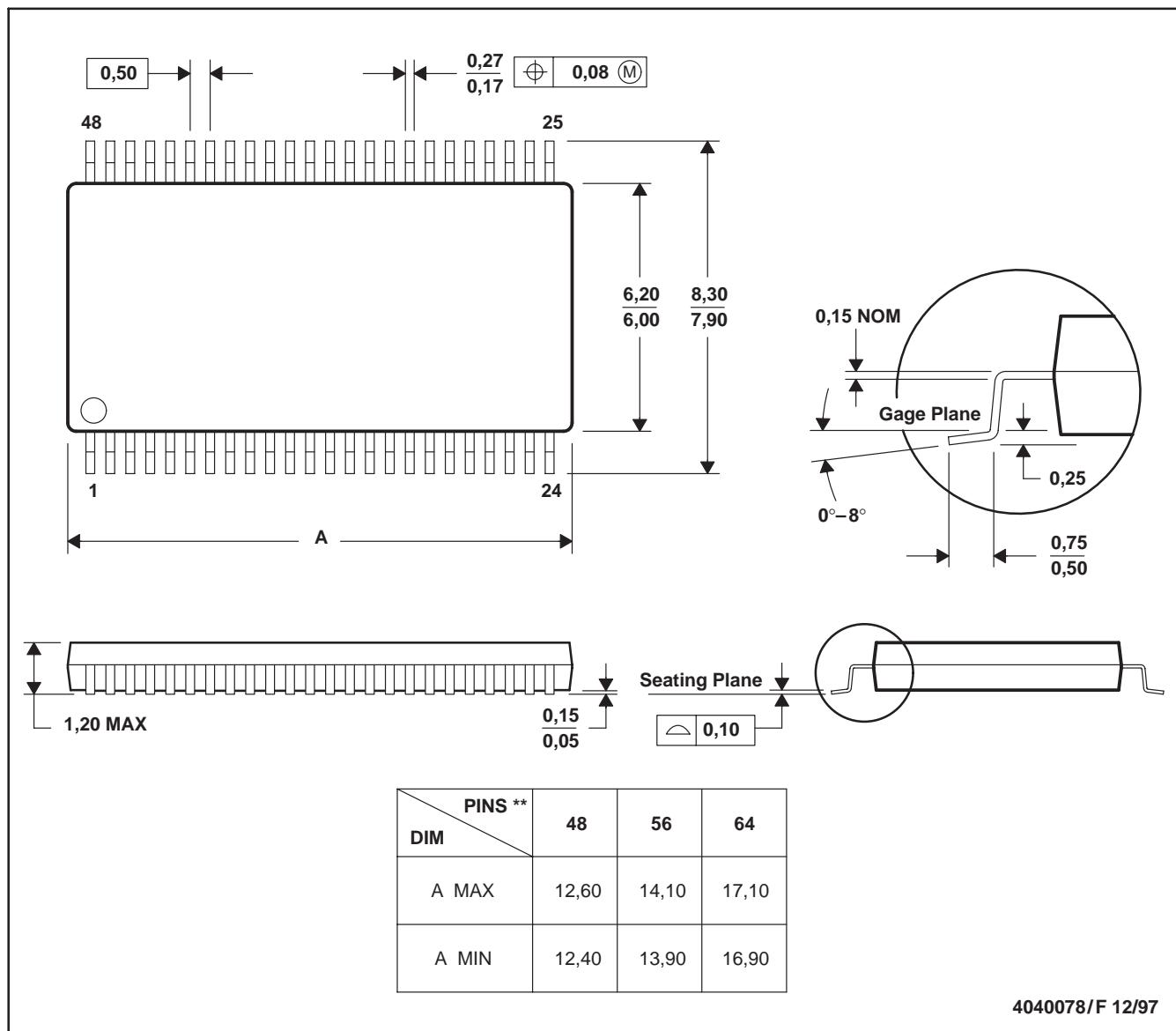
NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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